

METHOD AND SYSTEM FOR COOLING RESIN-SEALED SUBSTRATE, SYSTEM
FOR CONVEYING SUCH SUBSTRATE, AND RESIN-SEALING SYSTEM

ABSTRACT

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A system for cooling a resin-sealed substrate while preventing its warping is provided. The system includes: a holder 40 for holding a resin-sealed substrate 21A; an attracting device, provided in the holder, for attracting the resin-sealed substrate 21A; and a cooling member 31, located at a position toward which the attracting device attracts the
10 resin-sealed substrate 21A, the cooling member 31 having a contact surface with which the resin-sealed substrate 21A tightly contacts. The attracting device includes: an elastic support 32 for forming a closed space between the resin-sealed substrate and the contact surface; a through-hole 33a which is provided in the cooling member 31 at a position within the aforementioned closed space and penetrates through the cooling member 31 in the thickness
15 direction thereof; and an air-sucking device 33c for drawing air from the closed space through the through-hole 33a and the air-sucking channel 33b.

FIGURE 4